

ABSTRACT OF THE DISCLOSURE

A micro-etching composition and a printed circuit board fabricated by using the micro-etching composition are provided.

- 5 The micro-etching composition, comprising a main ingredient consisting of sulfuric acid and hydrogen peroxide and an assisting ingredient consisting of phenyltetrazole and a chloride ion source, can continuously treat the surface of copper and copper alloys to produce fine microscopic pits for  
10 improved adhesion to resins without producing a brown or black deposit. The printed circuit board exhibits excellent adhesion between inner layer circuit patterns and insulation resin layers, and is free from haloing.